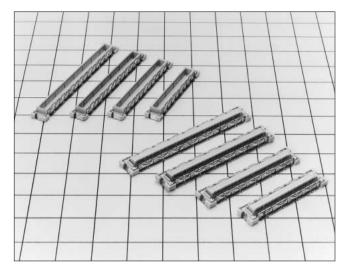
0.5mm Pitch Connectors with Ground Plate for Board-to-Board Connections

FX10 Series

NEW



Features

1. Improved Transmission Efficiency Between Boards

Transmission characteristics have been improved through a design that fixes ground plates to both sides of the header and receptacle.

2. 10 Signal:1 Ground Arrangement

Signal and ground are arranged in a ratio of 10:1 with the ground plate SMT connected to the board. The ground stability achieved serves to reduce noise.

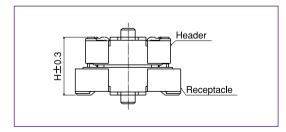
3. Reinforced Fittings for Added Solder Weld Strength

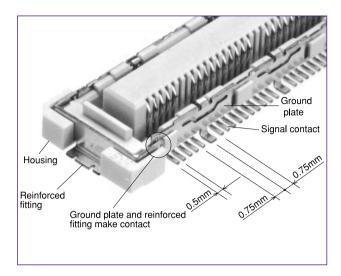
Reinforced fittings provide greater adhesion to the board, protecting against peeling. The unique connector design provides a connection between the fitting and the ground plate for a stronger ground.

4. Suited to High-Density Applications

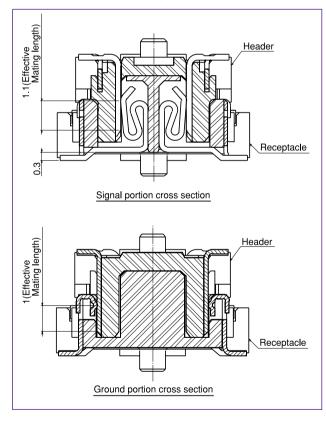
The signal contact pitch of 0.5 mm produces a smaller connector utilizing less board area for mounting.

5. Board-To-Board Dimensions of 4mm and 5 mm Are Available





Cross-Section of Mating



Stack Height

Receptacles	FX10# -*S/*-SV			
Headers	Dimension H			
FX10#*P/*-SV1	4mm			
FX10#*P/*-SV1	5mm			

Note: The thickness of the solder paste is not included in the stack height (dimension H).

Applications

Notebook computers, PDA, and other miniature electronic equipment.

Product Specifications

	Rating	Rated current Rated voltage	0.3 A (Note 1)	Operating temperature range Operating humidity range	Relative humidity 95% or less	Storage temperature range Storage humidity range	-10 to +60°C (Note 2) 40 to 70% (Note 2)	
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Item	Requirements	Conditions
1. Insulation resistance	100 MΩ or greater	Measured at 100 V DC
2. Voltage proof	No flashover or breakdown	150 V AC applied for one minute
3. Contact resistance	60 mΩ or less	Measured at 100 mA
4 Mihrotian	No electrical discontinuity for 1µs or greater	Frequency: 10 to 55 Hz, amplitude of 0.75 mm in 3 directions, 10
4. Vibration	No damage, cracks, or parts looseness	cycles each
	No electrical discontinuity for 1µs or longer	Acceleration of 490 m/s ² , 11 ms duration, sine half-wave
5. Shock	No damage, cracks, or parts looseness	waveform, for 3 cycles in the both directions of each of the 3 axes
6. Damp heat	Contact resistance of 70 m Ω or less, insulation resistance of	
(Steady state)	100 $\ensuremath{M\Omega}$ or greater, no damage, cracks, or parts looseness	Temperature of 40°C, humidity of 90 to 95%, duration 96 h
7. Rapid change of	Contact resistance of 70 m $\!\Omega$ or less, insulation resistance of	Temperature: -55° C \rightarrow 15 to 35° C \rightarrow 85 $^{\circ}$ C \rightarrow 15 to 35° C
temperature	100 $M\Omega$ or greater, no damage, cracks, or parts looseness	Time: 30 min. \rightarrow 2 to 3 min. \rightarrow 30 min. \rightarrow 2 to 3 min. for 5 cycles
	Contact resistance of 70 m or less	50 times
8. Insertion/Withdrawal life	No damage, cracks, or parts looseness	50 times
9. Resistance to		Reflow: At the recommended temperature profile
soldering heat	No melting of resin portion which affects performance	Soldering iron temperature: 300°C.for 3 seconds

Note 1: Please contact us when connector application exceeds 0.3 A rated current.

Note 2: The term storage refers to an unused products prior to board mounting (including packing materials) that is being kept for a long period. The operating temperature and humidity range are suited to the non-conducting condition following board assembly.

Note 3: The aforementioned specifications are representative of this series. For information on specific parts, confirm with Sales Office.

Materials

Part	Material	Process		Notes	
Insulator	LCP resin		Beige		
Oranteate		Header	Engagement Area: Gold plating of 0.1µm		
	Phosphor bronze	Header	Tenmination Area: Solder plating	—	
Contacts		Decenterale	Engagement Area: Gold plating of 0.1m		
		Receptacle	Termination Area: Flash plating		
Ground plate	Phosphor bronze	Solder plating			
Reinforced fitting	Phosphor bronze				

Note : The black dots on the insulater will not affect performance.

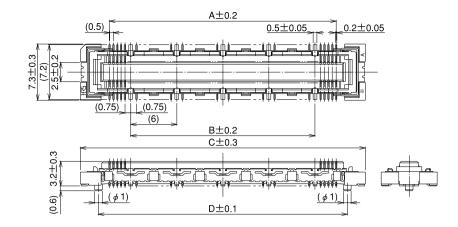
Product Number Configuration

Please use this information to discern the product specifications from the product number codes. To order, please select from the product number codes listed in tables on pages 3 to 5 of this catalog.

FX 10 #- *P	/ * - SV 1 (* *)				
000					
4					
 Series name: FX 	6 Contact form				
Series No.: 10	SV: Straight SMT				
6 Form Symbol	Product height				
A: With guide post	Blank: Standard				
B: Without guide post	1 : Standard + 1mm				
4 Number of contacts	8 Packaging classification				
Signal/Ground: 80/8, 100/10, 120/12,	Blank: Tray packaging				
140/14	(21) : Embossed tape packaging				
G Connector type					
P: Header					
S: Receptacle					

Receptacles





Unit: mm

HRS No.	Product No.		f Contacts Ground	Α	В	С	D	E	F	Notes
CL570-0201-4-* *	FX10A- 80S/ 8-SV(* *)	80	8	23.5	18	31.1	26.4	31.5	28.3	
CL570-0202-7-* *	FX10A-100S/10-SV(* *)	100	10	29.5	24	37.1	32.4	37.5	34.3	
CL570-0203-0-* *	FX10A-120S/12-SV(* *)	120	12	35.5	30	43.1	38.4	43.5	40.3	With guideposts
CL570-0204-2-* *	FX10A-140S/14-SV(* *)	140	14	41.5	36	49.1	44.4	49.5	46.3	
CL570-0221-1-* *	FX10B- 80S/ 8-SV(* *)	80	8	23.5	18	31.1	-	31.5	28.3	
CL570-0222-4-* *	FX10B-100S/10-SV(* *)	100	10	29.5	24	37.1	-	37.5	34.3	Without guidenosta
CL570-0223-7-* *	FX10B-120S/12-SV(* *)	120	12	35.5	30	43.1	_	43.5	40.3	Without guideposts
CL570-0224-0-* *	FX10B-140S/14-SV(* *)	140	14	41.5	36	49.1	-	49.5	46.3	

[Specifications number]- * *,(* *)

Blank: Tray packaging

(21) :Embossed tape packaging

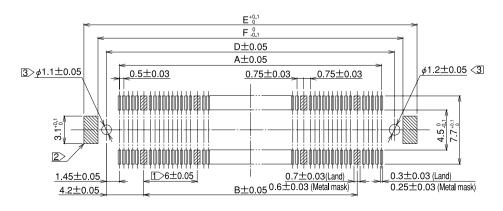
Note 1: There is no polarity in terms of board mounting for this product.

Note 2: The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3: Please order embossed tape packaged items by the reel. (One reel holds 1,000 pieces.)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)

Recommended metal mask thickness: 0.15 mm



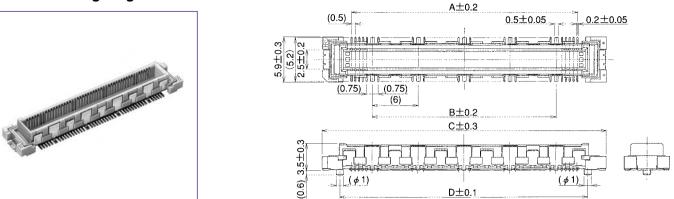
Note 1 Cross-hatched portions, totaling n places, indicate the ground circuits.

2 Cross-hatched portions, 2 places on both sides, indicate the reinforced fittings.

 $\boxed{3}$ Not required in products without guideposts.

Headers

•4mm Mounting Height



Unit: mm

HRS No.	Product No.	Number o Signal	f Contacts Ground	A	В	С	D	E	F	Notes	
CL570-0001-5-* *	FX10A- 80P/ 8-SV(**)	80	8	23.5	18	31.1	26.4	31.5	28.3		
CL570-0002-8-* *	FX10A-100P/10-SV(* *)	100	10	29.5	24	37.1	32.4	37.5	34.3	With guideneete	
CL570-0003-0-* *	FX10A-120P/12-SV(* *)	120	12	35.5	30	43.1	38.4	43.5	40.3	With guideposts	
CL570-0004-3-* *	FX10A-140P/14-SV(* *)	140	14	41.5	36	49.1	44.4	49.5	46.3	46.3	
CL570-0021-2-* *	FX10B- 80P/ 8-SV(**)	80	8	23.5	18	31.1	-	31.5	28.3		
CL570-0022-5-* *	FX10B-100P/10-SV(* *)	100	10	29.5	24	37.1	-	37.5	34.3		
CL570-0023-8-* *	FX10B-120P/12-SV(* *)	120	12	35.5	30	43.1	-	43.5	40.3	Without guideposts	
CL570-0024-0-**	FX10B-140P/14-SV(**)	140	14	41.5	36	49.1	-	49.5	46.3		

[Specifications number] -* *, (* *)

Blank: Tray packaging

(21) : Embossed tape packaging

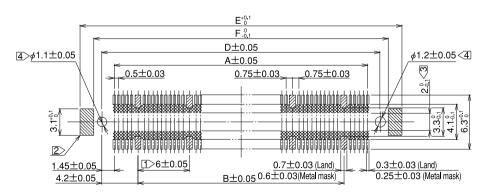
Note 1: There is no polarity in terms of board mounting for this product.

Note 2: The coplanarity of this product's SMT leads is 0.1mm or less.

Note 3: Please order embossed tape packaged items by the reel. (One reel holds 1,000 pieces.)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)

Recommended metal mask thickness: 0.15 mm

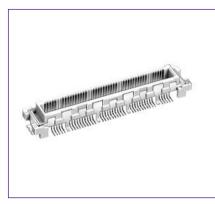


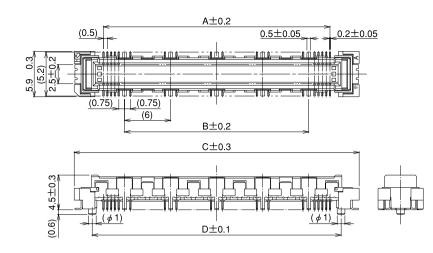
Note 1 Cross-hatched portions, totaling n places, indicate the ground circuits.

- 2 Cross-hatched portions, 2 places on both sides, indicate the reinforced fittings.
- 3 The cross-hatched area inside the SMT land may come into contact with the connector contacts
- and thus care should be taken that the pattern does not extend beyond the SMT land width.
- $\boxed{4}$ Not required in products without guideposts.

Headers

•5mm Mounting Height





Unit: mm

HRS No.	Product No.		f Contacts Ground	Α	В	с	D	E	F	Notes
CL570-0101-0-* *	FX10A- 80P/ 8-SV1(**)	80	8	23.5	18	31.1	26.4	31.5	28.3	
CL570-0102-2-* *	FX10A-100P/10-SV1(* *)	100	10	29.5	24	37.1	32.4	37.5	34.3	
CL570-0103-5-* *	FX10A-120P/12-SV1(* *)	120	12	35.5	30	43.1	38.4	43.5	40.3	With guideposts
CL570-0104-8-* *	FX10A-140P/14-SV1(* *)	140	14	41.5	36	49.1	44.4	49.5	46.3	
CL570-0121-7-* *	FX10B- 80P/ 8-SV1(**)	80	8	23.5	18	31.1	-	31.5	28.3	
CL570-0122-0-* *	FX10B-100P/10-SV1(* *)	100	10	29.5	24	37.1	-	37.5	34.3	Without guideneete
CL570-0123-2-* *	FX10B-120P/12-SV1(* *)	120	12	35.5	30	43.1	-	43.5	40.3	Without guideposts
CL570-0124-5-* *	FX10B-140P/14-SV1(**)	140	14	41.5	36	49.1	-	49.5	46.3	

[Specifications number] -* *,(* *)

Blank: Tray packaging

(21) : Embossed tape packaging

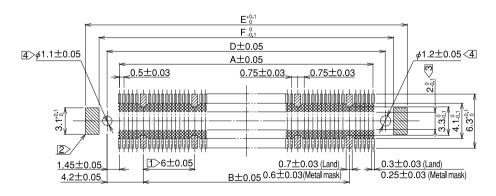
Note 1: There is no polarity in terms of board mounting for this product.

Note 2: The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3: Please order embossed tape packaged items by the reel. (One reel holds 1,000 pieces.)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)

Recommended metal mask thickness: 0.15 mm



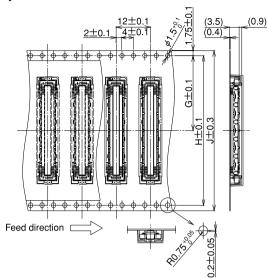
Note 1 Cross-hatched portions, totaling n places, indicate the ground circuits.

- 2 Cross-hatched portions, 2 places on both sides, indicate the reinforced fittings.
- 3 The cross-hatched area 🖾 inside the SMT land may come into contact with the connector contacts
- and thus care should be taken that the pattern does not extend beyond the SMT land width.
- $\boxed{4}$ Not required in products without guideposts.

Embossed Carrier Tape Dimensions

Receptacles

Headers



 12 ± 0.1

, <u>,</u>

(K)

Insertion Connector	G	H	J	L	M	N
FX10#- 80S/ 8-SV	20.2	40.4	44	330	45.5	50.5
FX10#-100S/10-SV	26.2	52.4	56	330	59	64
FX10#-120S/12-SV	26.2	52.4	56	330	59	64
FX10#-140S/14-SV	34.2	68.4	72	330	76.5	81.5
Nister There is a second			(1.4

Note: There is no polarity in terms of embossed tape packaging for this product.

$2\pm 0.1 4\pm 0.1 5 1 (0.4)$	
<u>₽</u> = <u>₹</u> · <u></u> <u></u> <u></u> <u></u>	Insert
	FX10
	FX10
	FX10
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	FX10#
	FX10#
	FX10#
	FX10#
	Note:
	F

(0.9)

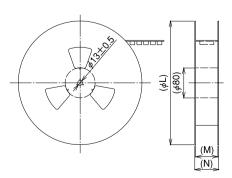
rtion Connector G Н J Κ L Μ Ν 0#- 80P/ 8-SV 20.2 40.4 44 3.8 330 45.5 50.5 0#-100P/10-SV 26.2 52.4 56 3.8 330 59 64 0#-120P/12-SV 26.2 52.4 56 3.8 330 59 64 0#-140P/14-SV 34.2 68.4 72 3.8 330 76.5 81.5 #- 80P/ 8-SV1 20.2 40.4 44 4.8 370 45.5 50.5)#-100P/10-SV1 26.2 52.4 56 4.8 370 59 64 #-120P/12-SV1 26.2 52.4 4.8 370 59 56 64)#-140P/14-SV1 34.2 68.4 72 4.8 370 76.5 81.5

Note: There is no polarity in terms of embossed tape packaging for this product.

Reel Packaging Dimensions

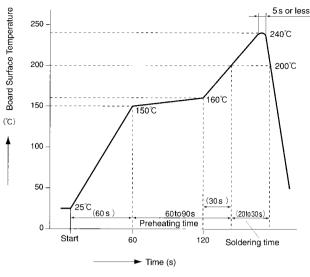
Feed direction

- 6 6 6 6



Recommended Temperature Profile

This temperature profile is a reference for the setting conditions described below. It will differ depending on conditions and so mounting should follow verification.



Applicable Conditions								
Reflow method	:	IR reflow						
Solder	:	Cream type 63Sn/37Pb						
		(Flux component of 9wt%)						
Test substrate	:	Glass epoxy. 85 x 110 x 1.6mm						
Metal mask thickness	:	0.15mm						

This temperature profile is a recommendation. Conditions may change somewhat depending on the type of cream solder and the amount.

HC5 7

Washing Conditions

Organic Solvent Washing

Solvent	Room temperature washing	Heated washing
IPA (Isopropyl alcohol)	Yes	Yes
HCFC (Hydrochlorofluorocarbon)	Yes	Yes

Water Type Washing

When using water type cleaning agents (e.g., terpene, and alkali saponifiers), select the cleaning agent based on the documentation issued by the various manufacturers of cleaning agents which describes the effects on metals and resins. Be careful that parts are not left with moisture remaining on them.

Washing Precautions

Residual flux or cleaning agent on the contacts when washing with organic solvents or water type cleaners can give rise to the deterioration of electrical performance. In this regard it is important to check whether a thorough washing has been performed.

Connector Handling Precautions

1. Allowable Creepage Dimensions at Time of Mating

The effective coupling length of this product is 1.1 mm for the signal portion and 1 mm for the ground portion. The creepage of the header and receptacle at the time of mating should be within 0.5 mm of the completely coupled condition.

2. Retension of Boards

Avoid the support of boards by connectors alone and adopt a locking measure that does not rely on the connectors.

3. Solder Repair

Flux may rise as far as the contact portion of the connector depending on the flux coating and other factors at the time of repair. This will cause poor contact reliability; therefore, before use, the aforementioned washing conditions should be taken into consideration prior to connector washing.

4. Miscellaneous

•Note that excessive twisting while inserting or withdrawing connectors will cause damage.

Connector width	Connector length
Board	direction

The shade of the molded items may vary somewhat depending on the manufacturing lot; however, this does not affect performance.